

N-Channel Super Junction Power MOSFET $\,\,{\rm IV}$

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

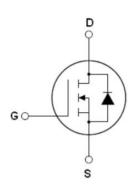
Features

- •New technology for high voltage device
- •Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested
- ●ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

V _{DS min@Tjmax}	550	V
RDS(ON)TYP.	520	mΩ
ID	6.3	A
Qg	9.5	nC



Schematic diagram

♦ Intrinsic fast-recovery body diode

TO-252

Package Marking And Ordering Information

0	V	
Device	Device Package	Marking
NCE50NF600K	TO-252-2L	NCE50NF600K

Table 1. Absolute Maximum Ratings (Tc=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGs=0V)	VDS	500	V
Gate-Source Voltage (V _{DS} =0V) ,AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDs=0V) ,DC	Vgs	±20	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	6.3	A
Continuous Drain Current at Tc=100°C	I _{D (DC)}	4.41	A
Pulsed drain current ^(Note 1)	I _{DM (pluse)}	18.9	A
Maximum Power Dissipation(Tc=25°C)	PD	74	W
Derate above 25°C		0.49	W/°C
Single pulse avalanche current (Note 2)	I _{AS}	2.5	A
Reverse diode dv/dt, $V_{DS} \leqslant 480 V, I_{SD} < I_D$	dv/dt	15	V/ns
Drain Source voltage slope, $V_{DS} \leqslant 480 V$	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	TJ,TSTG	-55+175	°C



Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	2.02	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	°C /W

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250uA	500			V
Zero Gate Voltage Drain Current(Tc=25°C)	I _{DSS}	V _{DS} =500V,V _{GS} =0V			10	μA
Zero Gate Voltage Drain Current(Tc=125°C)	I _{DSS}	V _{DS} =500V,V _{GS} =0V			300	μA
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20V, V_{DS} =0V			±200	nA
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_D=250$ uA	3		5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V_{GS} =10V, I_D =3A		520	600	mΩ
Dynamic Characteristics						
Gate Resistance	Rg	F=1MHZ, D-S short		35		Ω
Input Capacitance	C _{lss}			317		pF
Output Capacitance	Coss	V_{DS} =50V, V_{GS} =0V,		22		pF
Reverse Transfer Capacitance	C _{rss}	F=1MHz		2.8		pF
Total Gate Charge	Qg			9.5		nC
Gate-Source Charge	Q _{gs}	V _{DS} =350V,I _D =3A,		4.2		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V		2.8		nC
Gate plateau voltage	Vgp			7		V
Switching times						
Turn-on Delay Time	t _{d(on)}			8		nS
Turn-on Rise Time	tr	V_{DD} =380V,I _D =3A,		9		nS
Turn-Off Delay Time	t _{d(off)}	R _G =4Ω,V _{GS} =10V		40		nS
Turn-Off Fall Time	t _f			9		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I _{SD}	T05°O			6.3	А
Pulsed-Source-drain current(Body Diode)	I _{SDM}	Tc=25°C			18.9	А
Forward on voltage	V _{SD}	Tj=25°C,I _{SD} =6.3A,V _{GS} =0V 1.0		1.0	1.2	V
Reverse Recovery Time	t _{rr}			100		nS
Reverse Recovery Charge	Q _{rr}	Tj=25°C,IF3A,		0.35		uC
Peak reverse recovery current	Irrm	di/dt=100A/µs		7		А

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25°C,VDD=50V,VG=10V, R_G=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure1. Safe operating area

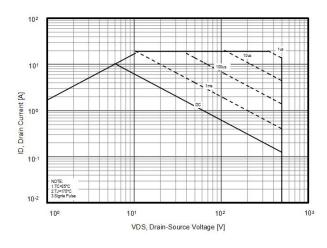


Figure3. Output characteristics

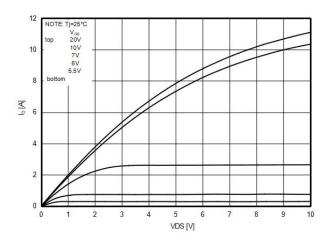


Figure5. Static drain-source on resistance

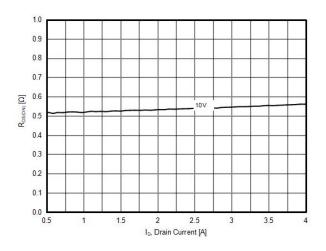


Figure2. Source-Drain Diode Forward Voltage

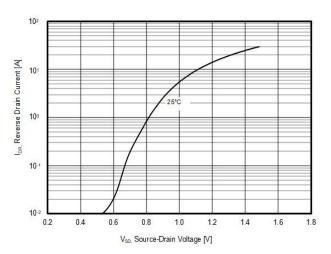


Figure4. Transfer characteristics

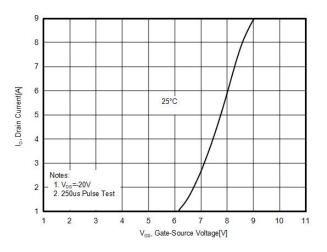


Figure6. RDS(ON) vs Junction Temperature

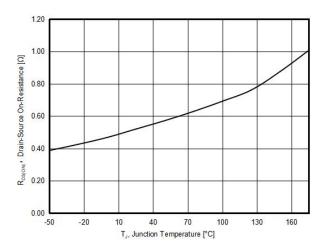




Figure7. BV_{DSS} vs Junction Temperature

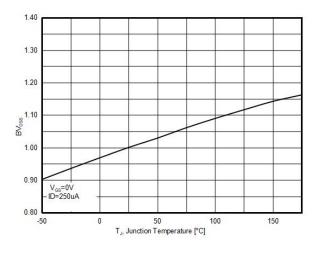


Figure8. Maximum I_D vs Junction Temperature

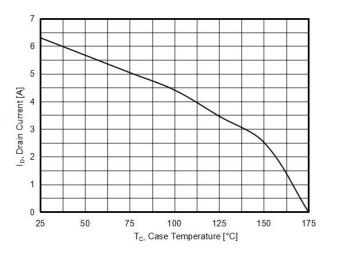


Figure9. Gate charge waveforms

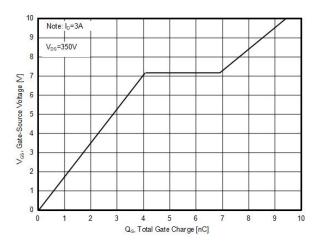
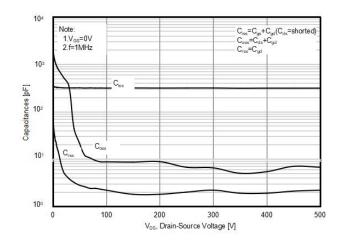


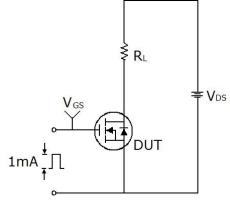
Figure10. Capacitance

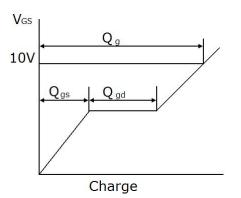




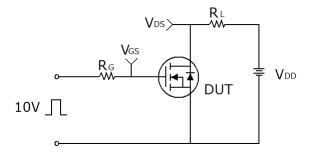
Test circuit

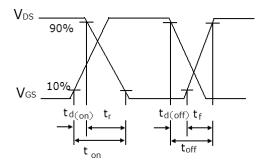
1) Gate charge test circuit & Waveform



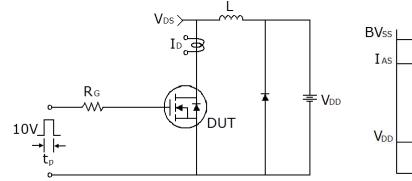


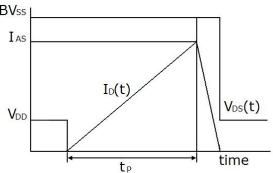
2) Switch Time Test Circuit:





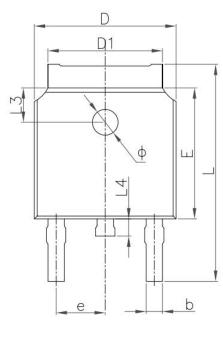
3) Unclamped Inductive Switching Test Circuit & Waveforms

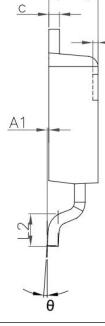




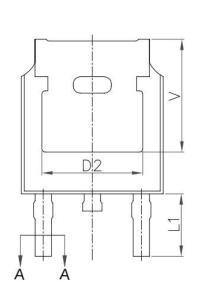


TO-252-E Package Information





h



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.20	2.40	0.087	0.094	
A1	0.00	0.13	0.000	0.005	
b	0.66	0.86	0.026	0.033	
b1	0.73	0.79	0.029	0.031	
С	0.46	0.58	0.018	0.023	
c1	0.50	0.52	0.020	0.020	
D	6.50	6.70	0.256	0.264	
D1	5.10	5.46	0.201	0.215	
D2	4.83 REF		0.19REF		
E	6.00	6.20	0.236 0.244		
е	2.19	2.39	0.086	0.094	
L	9.80	10.40	0.386	0.409	
L1	2.90	REF	0.11REF		
L2	1.40	1.70	0.055		
L3	1.60 REF		0.06REF		
L4	0.60	1.00	0.024	0.039	
Φ	1.10	1.30	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.00	0.30	0.000	0.012	



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